

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3508465	(die chip ic (integrated adj circuit) semiconductor dice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 23:07
L2	870124	(substrate carrier board pcb ((printed circuit wiring) adj4 board)) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 23:09
L3	63085	(middle center) with (bond pad bonding bonded)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 23:10
L4	4147	2 same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 23:10
L5	1563	(trace wiring lead) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 23:11
L6	1105	wire and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 23:11